



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-03-07
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	FLORIANA SAN BIAGIO	<b>Representative Title</b>	AMG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	3K07*UF75JC5	A	SH1A	2017-03-07
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9x3.9x1.75	8	gull wing	
Comment	Package: 07 SO 08 .15 JEDEC; MDF valid for ST485ERBDR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	3K07*UF75JCS					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.422	mg	supplier	die	Silicon (Si)	7440-21-3		4.258	mg	962913	53225
				supplier	metallization	Aluminium (Al)	7429-90-5		0.035	mg	7915	438
				supplier	metallization	Copper (Cu)	7440-50-8		0.001	mg	226	13
				supplier	Passivation	Silicon Nitride	12033-89-5		0.013	mg	2940	163
				supplier	Passivation	Silicon Oxide	7631-86-9		0.060	mg	13569	750
				supplier	polymer die coating	PIX1 Polyimide	108-65-6		0.008	mg	1809	100
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.047	mg	10629	588
				supplier	alloy	Copper (Cu)	7440-50-8		28.245	mg	964750	353063
Leadframe	Copper & its alloys	29.277	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.664	mg	22680	8300
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.040	mg	1366	500
				supplier	alloy	Zinc (Zn)	7440-66-6		0.035	mg	1195	438
				supplier	metallization	Nickel (Ni)	7440-02-0		0.268	mg	9154	3350
				supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	307	113
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	273	100
				supplier	metallization	Silver (Ag)	7440-22-4		0.008	mg	273	100
				supplier	glue	Silver (Ag)	7440-22-4		1.339	mg	877457	16738
Die attach	Other Organic Materials	1.526	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.076	mg	49803	950
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.076	mg	49803	950
				supplier	glue	Acrylate polymer	87320-05-6		0.031	mg	20315	388
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.002	mg	1311	25
				supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.002	mg	1311	25
				supplier	wire	Copper (Cu)	7440-50-8		0.054	mg	1000000	675
				supplier	mold compound	Silica, vitreous	60676-86-0		38.728	mg	865991	484100
				supplier	mold compound	Epoxy Resin	25068-38-6		3.354	mg	74998	41925
Encapsulation	Other Organic Materials	44.721	mg	supplier	mold compound	Phenol Resin	29690-82-2		2.236	mg	49999	27950
				supplier	mold compound	Carbon black	1333-86-4		0.224	mg	5009	2800
				supplier	mold compound	Bismuth compound	7440-69-9		0.179	mg	4003	2238
				supplier	mold compound							